

深圳市灿科盟实业有限公司

SHENZHEN CANKEMENG INDUSTRIAL CO. LTD

承 认 书

SPECIFICATION FOR APPROVAL

客户名称 CUSTOMER	
品 名 DESCRIPTION	针座/PHD/2.0mm 间距/双排/直插/米黄色
料 号 CUSERTOMER PART NO	W-2008SXXP-0200
日 期 DATE	

客户确认 (APPROVED SIGNATURES)

核准 (APPROVAL)	工程 (ENGINEERING)	品管 (QC)
承认结果： ☐ 承认 ☐ 不承认 ☐ 重新送样		

深圳市灿科盟实业有限公司

SHENZHEN CANKEMENG INDUSTRY CO. LTD

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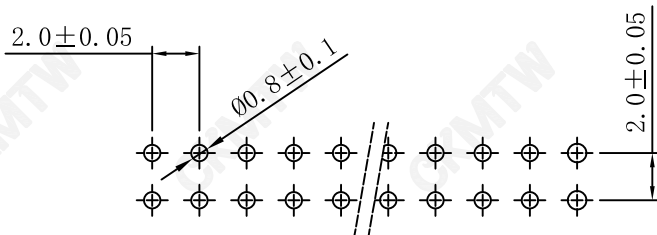
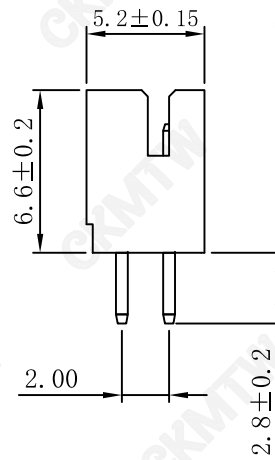
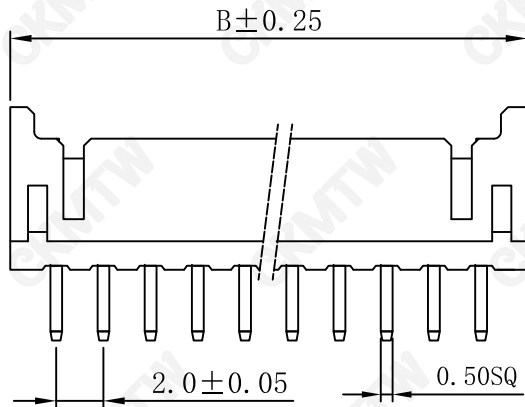
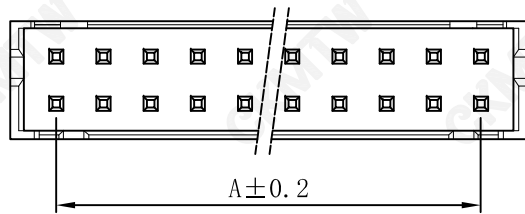
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生产基地：

江西灿科盟电子有限公司

JIANGXI CANKEMENG ELECTRONICS CO. LTD

公司地址 (Company address)：江西省九江市修水县渣津镇朴田
工业区



P. C. B LAYOUT

SPECIFICATIONS

Current rating: 2A

Voltage rating: 250V AC/DC

Contact resistance: 20mΩ max.

Withstand voltage: 800V AC/min

Insulation resistance: 1000MΩ/min.

Temperature range: -25°C~+85°C

Applicable PC board thickness: 0.031"~0.063"(0.8~1.6)

Material:

Part No: 8~40

Insulation Material: PA66 UL94-V0 (Beige)

Contact: Brass (Sn plating)

Finish: Tin Plated

Poles	Part No.	Dimension mm	
		A	B
8	W-2008S08P-0200	6.00	10.00
10	W-2008S10P-0200	8.00	12.00
12	W-2008S12P-0200	10.00	14.00
14	W-2008S14P-0200	12.00	16.00
16	W-2008S16P-0200	14.00	18.00
18	W-2008S18P-0200	16.00	20.00
20	W-2008S20P-0200	18.00	22.00
22	W-2008S22P-0200	20.00	24.00
24	W-2008S24P-0200	22.00	26.00
26	W-2008S26P-0200	24.00	28.00
28	W-2008S28P-0200	26.00	30.00
30	W-2008S30P-0200	28.00	32.00
32	W-2008S32P-0200	30.00	34.00
34	W-2008S34P-0200	32.00	36.00
36	W-2008S36P-0200	34.00	38.00
38	W-2008S38P-0200	36.00	40.00
40	W-2008S40P-0200	38.00	42.00

APPROVED:	DATE:	Ckmtw 深圳市灿科盟实业有限公司 CHANKEMENG INDUSTRY CO., LTD			
CHECKED:	DATE:	TITLE: 2008S-2*XP 米黄色			
DRAWN: SXA	DATE: 2018-03-16	PART. NO.	W-2008SXXP-0200		
		UNIT	mm	SCALE	free
		FILE NO.	Ckmtw-2008-0008	REV.	B KL00

TOLERANCE TABLE	
.0	±0.20
.00	±0.10
.000	±0.05

深圳市灿科盟实业有限公司

产 品 规 格 书

PRODUCT SPECIFICATION

2008 SERIES

内容：此规格书包含 2008（PHD2.0）线接基板系列。

Scope: This specification covers the 2008（PHD2.0） spacing Wire To Board Connector series.

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Note::以上测试视公司之测试条件/能力而定。

FILE NO	ENS004	APPROVAL	CHECK	DRAWING
ECR/N NO	New spec			

1. 产品名称及料号/Product name and part number

Product Name	Part Number
Terminal 端子	2008-T
Housing 母座	2008H-XP
Wafer Assembly ST 针座	2008S-XP (180°)、 2008R-XP (90°)

2. 额定电压电流及使用线径/Ratings and applicable wires

ITEM	STANDARD
Rated Voltage(Max) 额定电压 (最高)	250V DC/AC(rms)
Rated Current(Max) 额定电流 (最高)	2.0A
Applicable wires 使用线性	#28-#22
Applicable P.C.B hold dia 适用 PCB 板孔径	0.8~1.6mm
Ambient Temperature 使用温度范围	-25℃~+85℃

3. 特性测试/Performance

3-1. 电气特性/Electrical performance

ITEM	Test condition	Requirement
3-1-1 Contact Resistance 接触阻抗	Mate connectors, reassure by dry circuit ,20mV MAX,10mv.(Based upon JIS C5402 5.4) 将公母对插, 二头接上微电流电压测试。	0.02 欧 (MAX)
3-1-2 Insulation resistance 绝缘阻抗	Mate connectors, apply 500V DC between adjacent terminal or ground. (Based upon JIS C5402 5.2/MIL-STD-202 method 302 condition B) 将公母对插, 二头接上电压测试	1000 兆欧 (MIN)
3-1-3 Dielectric strength 高压测试	Mate connectors, apply 800V AC for 1 minute between adjacent terminal or ground. (Based upon JIS C5402 5.1/MIL-ST-202 Method 301) 将公母对插, 相邻的二支端子接上高压测试	No breakdown and flashover 没有损坏/没有电弧产生

3-2. 机械特性/Mechanical performance

ITEM		Test condition	Requirement			
3-2-1	Insertion force and withdrawal force 整组插拔测试	Insert and withdraw connectors at the speed rate of 25±3mm/minute 公母对插插拔 30 次，机器行走速度 25±3mm/分钟。	Insertion force: 0.4 kgf /PIN (MAX) Retention force: 0.1 kgf /PIN (MIN)			
3-2-2	Crimping pull out force 导电体保持力	Fix the crimped terminal, apply axial pull out force on the wire at the speed rate of 25±3mm/minute (Based upon JIS C5402 6.8) 端子固定住，将端子从线材拔出，机器行走速度 25±3mm/分钟。	Wire size	#24	#26	#28
			Crimp strength	2.3kg min	1.4kg min	0.9kg min

3-2-3	Terminal insertion force 插入力	Insert the crimped terminal into the housing 将端子插入胶壳，测试插入值	1.0kgf MAX
3-2-4	Terminal/Housing retention force 胶壳保持力	Apply axial pull out force at the speed rate of 25 ± 3 mm/minute on the terminal assembled In the housing. 将端子从胶壳中拔出，测试拔出值	0.8 kgf MIN
3-2-5	Pin retention force (单 PIN 保持力)	Apply axial push force at the speed rate of 25 ± 3 mm/minute. 将铜针从塑胶中推出，测试推出值	1.0kgf MIN

3-3.环境特性测试/Environmental performance and others

ITEM		Test condition	Requirement	
3-3-1	Repeated insertion/ withdrawal	When mated up to 30 cycles repeatedly by the rate of 10 cycles per minute 三十次插拔后，测量接触阻抗	Contact Resistance 接触阻抗	40mΩ MAX
3-3-2	Salt spray 盐水测试	12 hours exposure to a salt spray from the $5 \pm 1\%$ solution at $35 \pm 2^\circ\text{C}$. (Based upon JIS C5402/MIL-STD-202method 101D conditions. B) 时间 12 小时，盐水体比例 $5 \pm 1\%$ ，温度 $35 \pm 2^\circ\text{C}$ 。	Appearance	No Damage
			Contact Resistance	40mΩ MAX
3-3-3	Solderability 沾锡性测试	Soldering time: 3 ± 0.5 sec, solder temperature: $230 \pm 5^\circ\text{C}$ 时间: 3 ± 0.5 秒, 温度: $230 \pm 5^\circ\text{C}$	95%以上沾锡面积	
3-3-4	Resistance to soldering heat 焊热性测试	Soldering time: 5 ± 1 sec, solder temperature: $260 \pm 5^\circ\text{C}$ 时间: 5 ± 1 秒, 温度: $260 \pm 5^\circ\text{C}$	No Damage 外观没有影响	

4. 产品规格尺寸及材质/Product shape, dimensions and materials

(见附件图纸)